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FACSIMILE COVER SHEET

DATE:	May 20, 2002	FILE NO:	AMAT/4213.P1/ETCH/METAL/JB1	
TO:	Examiner Unknown		FAX NO:	703/746-4060
COMPANY:	UNITED STATES PATENT AND TRADEMARK OFFICE			
FROM:	Brian K. Hrma		PAGE(S): with cover	7
MESSAGE:			Original to Follow	NO

OFFICIAL FAX**TRUE COPY OF PREVIOUSLY SUBMITTED
RESPONSE TO NOTICE TO FILE MISSING PARTS**

U.S. Serial No.: 10/024,958
Confirmation No.: 3439
Filing Date: December 18, 2001
Inventors: Buie, et al.
Examiner: Unknown
Group Art Unit: 3723

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CONFIDENTIALITY NOTE

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UNITED STATES PATENT AND TRADEMARK OFFICE

COMMISSIONER FOR PATENTS
UNITED STATES PATENT AND TRADEMARK OFFICE
WASHINGTON, D.C. 20531
www.uspto.gov

APPLICATION NUMBER	FILING/RECEIPT DATE	FIRST NAMED APPLICANT	ATTORNEY DOCKET NUMBER
10/024,958	12/18/2001	Melissa Bute	004213 USA PPO1/ETCH/META

PATENT COUNSEL
APPLIED MATERIALS, INC.
Legal Affairs Department
P.O. BOX 450A
Santa Clara, CA 95052

REC'D MAY 13 2002

CONFIRMATION NO. 3439
FORMALITIES LETTER



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Date Mailed: 05/08/2002

NOTICE OF INCOMPLETE REPLY (NONPROVISIONAL)

Filing Date Granted

The U.S. Patent and Trademark Office has received your reply on 04/16/2002 to the Notice to File Missing Parts (Notice) mailed 03/18/2002 and it has been entered into the nonprovisional application. The reply, however, does not include the following items required in the Notice.

The period of reply remains as set forth in the Notice. You may, however, obtain EXTENSIONS OF TIME under the provisions of 37 CFR 1.136 (a) accompanied by the appropriate fee (37 CFR 1.17(a)).

A complete reply must be timely filed to prevent ABANDONMENT of the above-identified application.

The application is Informal since it does not comply with the regulations for the reason(s) indicated below.

The required item(s) identified below must be timely submitted to avoid abandonment

- Abstract must be on a separate sheet.

RE

*A copy of this notice **MUST** be returned with the reply.*

S. Green

Customer Service Center
Initial Patent Examination Division (703) 308-1202

PART 2 - COPY TO BE RETURNED WITH RESPONSE

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Buie, et al.

Serial No.: 10/024,958

Confirmation No.: 3439

Filed: December 18, 2001

For: Etch recess for Photolithographic
Reticle Manufacturing with
Improved Etch BiasAssistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Group Art Unit: 3723

Examiner: Unknown

CERTIFICATE OF FACSIMILE
TRANSMISSION UNDER 37 CFR 1.8I hereby certify that this correspondence and the documents referred to as
attached therein are being facsimile transmitted to the U.S. Patent and
Trademark Office to the fax number indicated by the Examiner, namely, fax
number 703/746-4060 to the attention of the named Examiner, on the date
below.6/5/2002
DateB. K. Hrna
SignatureTRUE COPY OF PREVIOUSLY SUBMITTED
RESPONSE TO NOTICE TO FILE MISSING PARTS

Applicants respectfully resubmit a true copy of a previously filed Supplemental Response to Notice to File Missing Parts dated March 18, 2002. The response was filed on April 17, 2002 to supplement an initial response received by the PTO on April 16, 2002. Attached is a true copy of the previously submitted response with a signed Certificate of Service dated April 17, 2002. Applicants have received a copy of the postcard receipt from the United States Patent and Trademark Office dated April 29, 2002. A copy of the postcard receipt is attached hereto. No fees are required for the submission of this Response to the Office Action.

Respectfully submitted,

B. K. Hrna

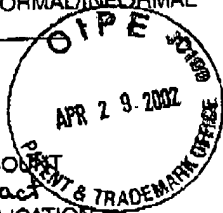
Brian K. Hrna
Registration No. 41,852
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Attorney for Applicant(s)

#7

DOCKET No.: AMAT/4213 P1/ETCH/METAL/JSB1
 SERIAL No.: 10/024,958
 FILED: December 18, 2001
 APPLICANT: Applied Materials, Inc.
 INVENTOR: Buie, et al

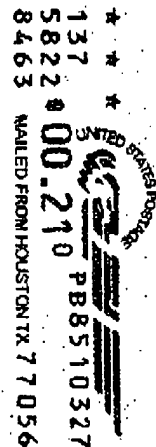
The Patent & Trademark Office acknowledges and has stamped
 hereon the date of receipt of the items checked below which were
 mailed April 17, 2002

- ☐ AFFIDAVIT
☐ AMENDMENT
☐ APPLICATION PAPERS - OATH/DECLARATION
☐ TOTAL CLS. _____ IND. CLS. _____ FEE \$ _____
☐ _____ SHEET(S) OF DRAWING(S) FORMAL/INFORMAL
☐ ASSIGNMENT-RECORDAL FEE \$ _____
☐ BRIEF
☐ APPEAL NOTICE
☐ DECLARATION
☐ ISSUE FEE - BASE/BALANCE
☐ LETTER - CHARGE DEPOSIT ACCOUNT
☒ LETTER - Replacement Abstract
☐ TRADEMARK/SERVICEMARK APPLICATION
☐ PETITION
☐ PRELIMINARY AMENDMENT
☐ INFORMATION DISCLOSURE STATEMENT
☐ REQUEST FOR EXTENSION OF TIME
☒ RESPONSE TO Notice to file Missing Parts
☐ SPECIMENS
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EXPRESS MAIL # _____ MAIL LOG # 10759
BKH

Moser, Patterson & Sheridan LLP
 3040 Post Oak Boulevard, #1500
 Houston, Texas 77056-6582



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Buie, et al.

Serial No.: 10/024,958

Confirmation No.: 3439

Filed: December 18, 2001

For: Etch Process for Photolithographic
Reticle Manufacturing with Improved
Etch Bias

Group Art Unit: 3723

Examiner: Unknown

Assistant Commissioner for Patents
Box MISSING PARTS
Washington, D.C. 20231

Dear Sir:

CERTIFICATE OF MAILING
37 CFR 1.8

I hereby certify that this correspondence is being deposited on
April 17, 2002 with the United States Postal Service as First
Class Mail in an envelope addressed to: Assistant
Commissioner for Patents, Washington, D.C. 20231.

4/17/02
Date

Keith M. Tackett
Signature

RESPONSE TO NOTICE TO FILE MISSING PARTS

Applicant files this Response to a Notice to File Missing Parts (Form PTO-1533), within the two-month period set to expire on May 18, 2002. The notice (copy enclosed) indicates that the application was filed without the abstract on a separate page.

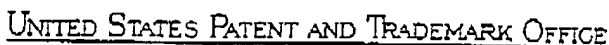
Enclosed for filing in the above-referenced application is the abstract on a separate page 25 in response to the missing parts request dated March 18, 2002, and partially responded to on April 9, 2002.

Although Applicant believes that no fee is due in conjunction with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/4213.P1/ETCH/METAL/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

Respectfully submitted,

Keith M. Tackett

Keith M. Tackett
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Attorney for Applicant



PATENT
Atty. Dkt. AMAT/5813/ETCH/METAL/JB
Replacement Page

ABSTRACT OF THE DISCLOSURE

Method and apparatus for etching a metal layer disposed on a substrate, such as a photolithographic reticle, are provided. In one aspect, a method is provided for processing a substrate including positioning a substrate having a metal photomask layer disposed on a silicon-based material in a processing chamber, introducing a processing gas comprising carbon monoxide, a chlorine containing gas, and optionally, an inert gas into the processing chamber, generating a plasma of the processing gas in the processing chamber, and etching exposed portions of the metal layer disposed on the substrate.

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